

| L Number | Hits | Search Text | DB | Time stamp |
|----------|------|---|---|------------------|
| 1 | 5891 | ((257/656) or (257/657) or (257/458) or (257/619) or (257/620) or (257/621) or (257/622) or (257/623) or (438/59) or (438/167) or (438/622)).CCLS. | USPAT; US-PGPUB; EPO; JPO; IBM_TDB | 2003/09/30 10:57 |
| 2 | 161 | ((257/656) or (257/657) or (257/458) or (257/619) or (257/620) or (257/621) or (257/622) or (257/623) or (438/59) or (438/167) or (438/622)).CCLS.) and (pin adj diode rectifier adj diode) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/30 10:58 |
| - | 0 | ("spitz.in.near2richard.in.").PN. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/30 09:00 |
| - | 42 | spitz.in. near2 richard.in. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/29 17:07 |
| - | 0 | rectifier adj diode and clock adj (frequency frequencies) and switching adj (rate time) and thickness.ti,ab,clm. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/29 17:09 |
| - | 4 | rectifier adj diode and clock adj (frequency frequencies) and switching adj (rate time) and thickness | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/29 17:10 |
| - | 433 | 257/101 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/29 17:12 |
| - | 354 | 257/104 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/29 17:19 |
| - | 3080 | rectifier adj diode.ti,ab,clm. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/29 17:20 |
| - | 86 | rectifier adj diode.ti,ab,clm. and thickness | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/29 17:40 |
| - | 2 | 914404.ap. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/29 18:26 |
| - | 2 | de-41352588-S.did. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/29 21:12 |
| - | 3 | ("4220963").PN. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/29 18:30 |
| - | 0 | ("fr-23199728-S.did.").PN. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/29 18:30 |

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| - | 0 | ("fr-2319972\$-\$\$.did.") .PN. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/29 18:30 |
| - | 0 | fr-02319972\$-\$\$.did. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/29 18:31 |
| - | 1 | fr-2319972\$-\$\$.did. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/29 18:31 |
| - | 64 | rectifier adj diode.ti,ab,clm. and 257/\$9.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/29 21:20 |
| - | 272 | PIN adj diode.ti,ab,clm. and 257/\$9.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/29 21:28 |
| - | 510 | ((257/656) or (257/657)).CCLS. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/29 21:28 |
| - | 95 | ((257/656) or (257/657)).CCLS.) and 438/\$9.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/29 21:29 |
| - | 0 | metallisation near5 PIN adj diode near12 wafer near6 cutting | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/30 09:27 |
| - | 0 | street near12 dicing and metallization near12 backside | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/30 09:28 |
| - | 7 | street and (dice dicing) and metallization near12 backside | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/30 09:29 |
| - | 2 | ("5689091") .PN. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/30 09:30 |
| - | 20415 | (cut cutting dice dicing) near6 wafer | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/30 09:30 |
| - | 96 | (cut cutting dice dicing) near6 wafer and (metallization metallisation metallize metallise) near6 (top upper front top-side front-side) and (metallization metallisation metallise metallize) near6 (bottom lower back backside back-side) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/30 09:32 |

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|---|----|--|---|------------------|
| - | 50 | {cut cutting dice dicing} near6 wafer and (metallization metallisation metallize metallise) near6 (top upper front top-side front-side) and (metallization metallisation metallise metallize) near6 (bottom lower back backside back-side) and method.clm. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/30 09:33 |
| - | 15 | {cut cutting dice dicing} near6 wafer and (metallization metallisation metallize metallise) near6 (top upper front top-side front-side) and (metallization metallisation metallise metallize) near6 (bottom lower back backside back-side) and (method near6 (metal metallizing metallization)).clm. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/30 09:37 |
| - | 0 | {(method process) near12 (metallization metallizing metallising metallisation) near12 (cutting dicing cut dice)).ti,ab,clm. and street | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/30 09:38 |
| - | 36 | {(method process) near12 (metallization metallizing metallising metallisation) near12 (cutting dicing cut dice)).ti,ab,clm. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/30 09:38 |
| - | 14 | {(method process) near12 (metallization metallizing metallising metallisation) near12 (cutting dicing cut dice)).clm. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/30 09:43 |
| - | 0 | street near12 dicing near12 metallization | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/30 09:43 |
| - | 84 | dicing near12 metallization | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/30 09:43 |
| - | 7 | dicing near12 metallization.clm. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/30 10:48 |